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2827

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group

Art Unit: 2827

Attorney

Docket No.: TKA0029

Applicant: Hiroshi Kimura

Invention: SEMICONDUCTOR DEVICE, ITS
MANUFACTURING METHOD AND ELECTRODEPOSITION
FRAME

Serial No: 09/837,022


Filed: April 18, 2001

Examiner: Mitchell, James M.

Certificate Under 37 CFR 1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner of Patents, Washington, D.C. 20231

on August 20, 2002


Kitisri Sukhapinda

#4/a
9/5/02
JWm

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RESPONSE TO OFFICE ACTION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated May, 23, 2002 in connection with the above-identified application, please amend the application as follows:

IN THE CLAIMS

Please cancel claims 2 and 3, and substitute claims 1 and 5 with the following:

- 21
- (Amended) A semiconductor device comprising:
a semiconductor element bonded on a first metallic layer;
a wire for electrically connecting an electrode pad of the semiconductor element to a second metallic layer; and
a resin package for sealing said semiconductor element,
wherein rear surfaces of the first metallic layer and the second metallic layer are flush with a bottom of said resin package, and wherein said first metallic layer is thicker than said